



40V DUAL P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	Rds(on) Max	I _D Max T _A = +25°C
-40V	$25m\Omega$ @ V _{GS} = -10V	-7.6A
	$45m\Omega @ V_{GS} = -4.5V$	-6.0A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- Backlighting
- DC-DC Converters
- Printer Equipment

Features and Benefits

- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low R_{DS(ON)} Minimizes Conduction Losses
- Fast Switching Speed Minimizes Switching Losses
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Qsuffix) part. A listing can be found at <a href="https://www.diodes.com/products/automotive/automotive-automo
 - products/.
 This part is qualified to JEDEC standards (as references in
 - https://www.diodes.com/quality/product-definitions/

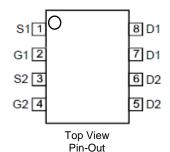
Mechanical Data

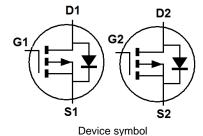
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Lead Frame. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.074 grams (Approximate)

AEC-Q) for High Reliability.









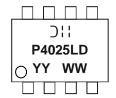
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP4025LSD-13	SO-8	2500 / Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



D\| = Manufacturer's Marking
P4025LD = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 21 = 2021)
WW = Week (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-40	
Gate-Source Voltage		Vgss	±20	V	
Continuous Drain Current	V _{GS} = -10V	(Notes 6 & 8)	lp	-7.6	
		T _A = +70°C (Notes 6 & 8)		-6.1	
		(Notes 5 & 8)		-5.8	
		(Notes 5 & 9)		-6.9	Α
Pulsed Drain Current	Vgs = -10V	(Notes 7 & 8)	I _{DM}	-28.0	
Continuous Source Current (Body Diode)		(Notes 6 & 8)	Is	-7.6	
Pulsed Source Current (Body Diode)		(Notes 7 & 8)	I _{SM}	-28.0	
Avalanche Current (Note 8)	L = 0.3mH	(Note 11)	las	-23	Α
Avalanche Energy (Note 8) I	L = 0.3mH	(Note 11)	Eas	79	mJ

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

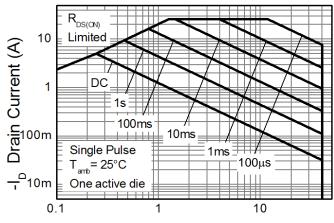
Characteristic		Symbol	Value	Unit	
D 0: 1 1:	(Notes 6 & 8)		2.14	W	
Power Dissipation Linear Derating Factor	(Notes 5 & 8)	PD	1.25		
Lineal Defaulty ractor	(Notes 5 & 9)		1.8		
	(Notes 6 & 8)		58		
Thermal Resistance, Junction to Ambient	(Notes 5 & 8)	R _{0JA}	100	90044	
	(Notes 5 & 9)		70	°C/W	
Thermal Resistance, Junction to Lead (Notes 8 & 10)		Rejl	51		
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

Notes:

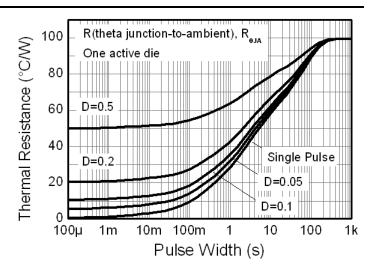
- 5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 6. Same as note (5), except the device is measured at $t \le 10$ sec.
- 7. Same as note (5), except the device is pulsed with D = 0.02 and pulse width 300 μ s.
- 8. For a dual device with one active die.
- 9. For a device with two active die running at equal power.
- 10. Thermal resistance from junction to solder-point (at the end of the drain lead).
- 11. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.



Thermal Characteristics

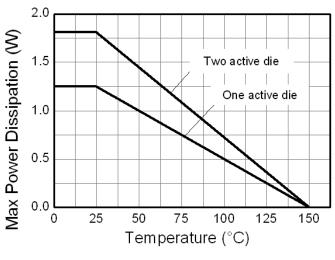


-V_{DS} Drain-Source Voltage (V)

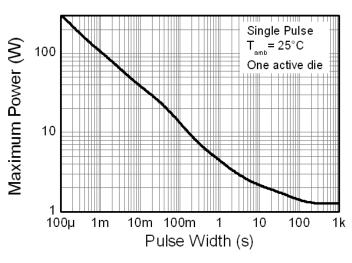


Transient Thermal Impedance

P-channel Safe Operating Area



Derating Curve



Pulse Power Dissipation



Electrical Characteristics ($@T_A = +25$ °C, unless otherwise specified.)

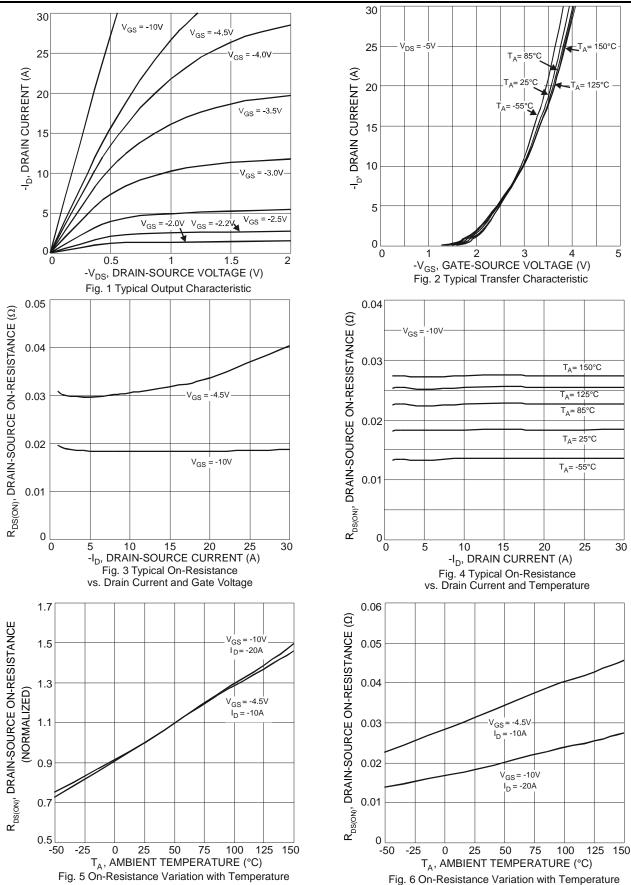
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	-40	_	_	V	I _D = -250µA, V _G S = 0V	
Zero Gate Voltage Drain Current	IDSS	_	_	-1.0	μΑ	V _{DS} = -40V, V _{GS} = 0V	
Gate-Source Leakage	Igss	_	_	±100	nA	Vgs = ±20V, Vps = 0V	
ON CHARACTERISTICS			•	•	•		
Gate Threshold Voltage	VGS(TH)	-0.8	-1.3	-1.8	V	I _D = -250µA, V _{DS} = V _{GS}	
Chatia Dunin Causas On Basistanas (Nata 40)	7		18	25	_	VGS = -10V, ID = -3A	
Static Drain-Source On-Resistance (Note 12)	RDS(ON)		30	45	mΩ	V _{GS} = -4.5V, I _D = -3A	
Forward Transconductance (Notes 12 & 13)	g FS	_	16.6	_	S	V _{DS} = -5V, I _D = -3A	
Diode Forward Voltage (Note 12)	V _{SD}	_	-0.7	-1.0	V	I _S = -1A, V _{GS} = 0V	
DYNAMIC CHARACTERISTICS (Note 13)	•						
Input Capacitance	Ciss	_	1640	_			
Output Capacitance	Coss	_	179	_	pF $V_{DS} = -20V, V_{GS} = 0V$ $f = 1MHz$		
Reverse Transfer Capacitance	Crss	_	128	_		T = TIVIHZ	
Gate Resistance	Rg	_	6.43	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (Note 14)	Qg	_	14.0	_		Vgs = -4.5V	
Total Gate Charge (Note 14)	Qg	_	33.7	_	0	V _{DS} = -20V	
Gate-Source Charge (Note 14)	Qgs		5.5	_	nC	V _{GS} = -10V I _D = -3A	
Gate-Drain Charge (Note 14)	Qgd	_	7.3	_			
Turn-On Delay Time (Note 14)	tD(ON)	_	6.9	_		<u>'</u>	
Turn-On Rise Time (Note 14)	t _R	_	14.7	_	$V_{DD} = -20V, V_{GS} = -10V$ $I_{D} = -3A$		
Turn-Off Delay Time (Note 14)	t _{D(OFF)}	_	53.7	_			
Turn-Off Fall Time (Note 14)	tF	_	30.9				

Notes:

^{12.} Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%.
13. For design aid only, not subject to production testing.
14. Switching characteristics are independent of operating junction temperatures.



Typical Characteristics





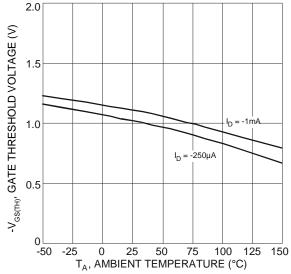
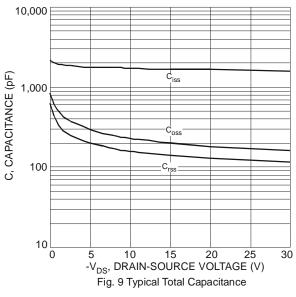
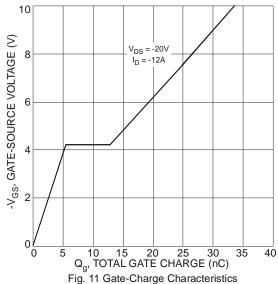
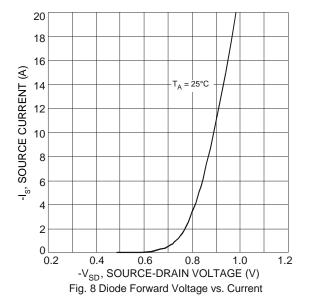
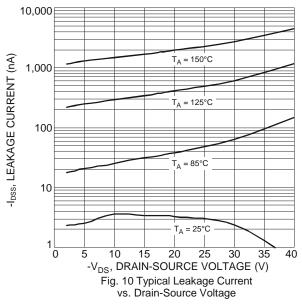


Fig. 7 Gate Threshold Variation vs. Ambient Temperature





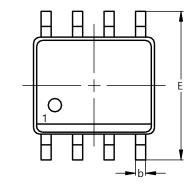


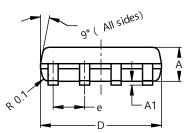


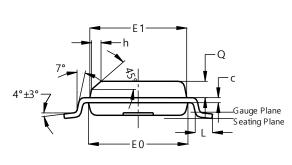


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.







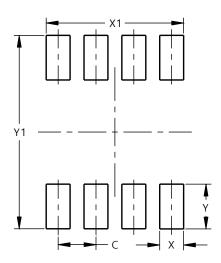
SO-8

SO-8						
Dim	Min	Max	Тур			
Α	1.40	1.50	1.45			
A1	0.10	0.20	0.15			
b	0.30	0.50	0.40			
C	0.15	0.25	0.20			
D	4.85	4.95	4.90			
Е	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
е			1.27			
h			0.35			
٦	0.62	0.82	0.72			
Ø	0.60	0.70	0.65			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.





Dimensions	Value (in mm)			
С	1.27			
Х	0.802			
X1	4.612			
Υ	1.505			
Y1	6.50			



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